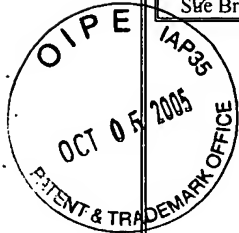


Certificate of Mailing Under 37 CFR 1.8

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Sue Bromaghin
Sue Bromaghin

October 3, 2005



CUSTOMER NO. 36257

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

Applicant: Wayne Glenn Renken
Title: System and Method for Heating and Cooling Wafer at Accelerated Rates
Application No.: 10/619,731 Filing Date: July 15, 2003
Examiner: Dhingra, Rakesh Kumar Group Art Unit: 1763
Docket No.: SENS.007US1 Conf. No.: 7022

Mail Stop Amendment
Commissioner for Patents
P.O. Box 1450
Alexandria, VA 22313-1450

10/06/2005 HTECKLU1 00000028 502664 10619731
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SUPPLEMENTAL INFORMATION DISCLOSURE STATEMENT

Sir:

Pursuant to 37 C.F.R. §§ 1.56, 1.97 and 1.98, Applicant(s) call(s) the documents listed on the enclosed Form PTO-1449 to the Examiner's attention in this patent application.

☒ According to 37 C.F.R. 1.98(2)(ii), copies of the U.S. Patents and U.S. Published Copies of the listed foreign patent documents or Other Art are enclosed.

Citation of these documents shall not be construed as (1) an admission that the documents are prior art with respect to the invention or inventions claimed in this application, (2) a representation that a search has been made (other than as indicated by any cited document), or

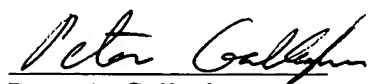
Attorney Docket No.: SENS.007US1

Application No.: 10/619,731

(3) an admission that the cited information is, or is considered to be, material to patentability as defined in § 1.56(b).

This information disclosure statement is submitted under 37 C.F.R. § 1.97(c). The fee authorization for \$180.00 for the information disclosure statement fee under 37 C.F.R. § 1.17(p), is enclosed.

Respectfully submitted,



Peter A. Gallagher
Reg. No. 47,584

10/3/05
Date

U.S. Department of Commerce, Patent and Trademark	Atty. Docket No.	Application No.
INFORMATION DISCLOSURE STATEMENT BY APPLICANT	SENS.007US1	10/619,731
(Use several sheets if necessary)	Applicant(s)	Conf. No.
(Form PTO-1449)	Wayne Glenn RENKEN	7022
	Filing Date	Art Group
	July 15, 2003	1763

U.S. Patent Documents

*Examiner Initial		Document Number	Date	Name	Class	Subclass	Filing Date If Appropriate
	1	4,685,331	08-1987	RENKEN et al.			
	2	5,670,218	09-1997	BAEK			
	3	6,494,955	12-2002	LEI et al.			

U.S. Published Patent Application Documents

*Examiner Initial		Document Number	Date	Name	Class	Subclass	Filing Date If Appropriate

Foreign Patent Documents

							Translation	
		Document	Date	Country	Class	Subclass	Yes	No

OTHER ART (Including Author, Title, Date, Pertinent Pages, Etc.)

	4	Smith et al., "Modeling the impact of thermal history during post exposure bake on the lithographic performance of chemically amplified resists", Proceeding of the SPIE, Vol. 4345, pp. 1013-1021 (2001), Advances in Resist Technology and Processing XVIII.

Examiner

Date Considered

*EXAMINER: Initial if reference considered, whether or not citation is in conformance with MPEP 609; Draw line through citation if not in conformance and not considered. Include copy of this form with your communication to applicant.